# Am27C128

16,384 x 8-Bit CMOS EPROM



#### DISTINCTIVE CHARACTERISTICS

- Fast access time -- 55 ns
- Low power consumption:
   100 at a maximum standbu
- 100 µA maximum standby current
- Programming voltage: 12.5 V
- Single +5-V power supply

- JEDEC-approved pinout
- ±10% power supply tolerance available
- One-Time Programmable (OTP) Flashrite<sup>TM</sup> programming
- Latch-up protected to 100 mA from −1 V to V<sub>CC</sub> +1 V

#### **GENERAL DESCRIPTION**

The Am27C128 is a 128K-bit, ultraviolet erasable programmable read-only memory. It is organized as 16,384 words by 8 bits per word, operates from a single +5-V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic DIP and LCC packages, as well as plastic one-time programmable (OTP) packages.

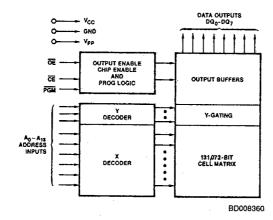
Typically, any byte can be accessed in less than 55 ns, allowing operation with high-performance microprocessors without any WAIT states. The Am27C128 offers separate Output Enable  $(\overline{\text{OE}})$  and Chip Enable  $(\overline{\text{CE}})$  controls, thus

eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 100 mW in active mode, and 250  $\mu\text{W}$  in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random. The Am27C128 supports AMD's interactive programming algorithm (1-ms pulses) resulting in typical programming times of less than two minutes.

#### **BLOCK DIAGRAM**



### PRODUCT SELECTOR GUIDE

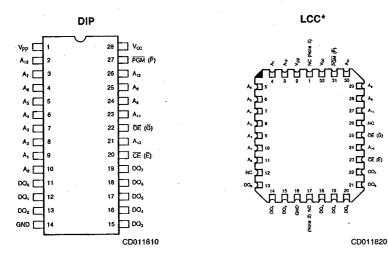
Family Part No.	Am27C128									
Ordering Part No:				Ţ			T			
±5% V <sub>CC</sub> Tolerance	-55	-75	-95	-125	-155	-205	~255	-305		
±10% V <sub>CC</sub> Tolerance	-	- 70	-90	-120	-150	-200	-250	-300		
Max. Access Time (ns)	. 55	70	90	120	150	200	250	300		
CE (E) Access (ns)	55	70	90	120	150	200	250	300		
OE (G) Access (ns)	35	40	40	50	65	75	100	120		

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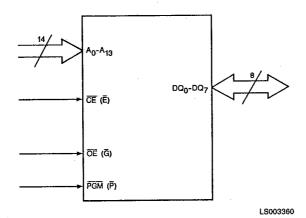
# CONNECTION DIAGRAMS Top View



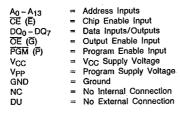
Notes: 1. JEDEC nomenclature is in parentheses 2. Don't use (DU) for PLCC.

\* Also available in 32-pin rectangular plastic leaded chip carrier.

#### LOGIC SYMBOL



#### PIN DESCRIPTION



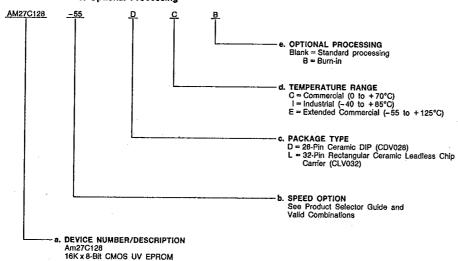
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#### **ORDERING INFORMATION**

#### Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid C	ombinations
AM27C128-55	
AM27C128-70	DC, DCB, LC, LCB
AM27C128-75	
AM27C128-95	
AM27C128-125	
AM27C128-155	DC, DCB, DI, DIB,
AM27C128-205	LC, LCB, LI, LIB
AM27C128-255	
AM27C128-305	7
AM27C128-90	
AM27C128-120	7
AM27C128-150	DC, DCB, DI, DIB,
AM27C128-200	DE, DEB, LC, LCB, LI, LIB, LE, LEB
AM27C128-250	7
AM27C128-300	7

#### Valid Combinations

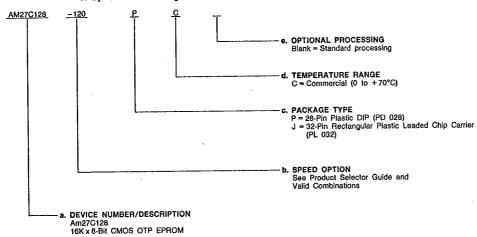
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

### ORDERING INFORMATION (Cont'd.)

### **OTP Products**

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid Combinations							
AM27C128-120							
AM27C128-125	7						
AM27C128-150							
AM27C128-155							
AM27C128-200	JC, PC						
AM27C128-205							
AM27C128-250							
AM27C128-255	<b>-</b>						
AM27C128-300							
AM27C128-305							

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

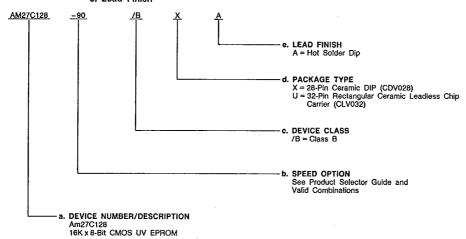


#### **MILITARY ORDERING INFORMATION**

#### **APL Products**

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Device Class
- d. Package Type
- e. Lead Finish



Valid Combinations						
AM27C128-90						
AM27C128-120						
AM27C128-150	/074 (2011					
AM27C128-200	/8XA, /8UA					
AM27C128-250						
AM27C128-300						

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, or to check for newly released valid combinations.

#### **Group A Tests**

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

#### **FUNCTIONAL DESCRIPTION**

#### Erasing the Am27C128

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C128 to an ultraviolet light source. A dosage of 15 W seconds/cm<sup>2</sup> is required to completely erase an Am27C128. This dosage can be obtained by exposure to an ultraviolet lamp - wavelength of 2537 Angstroms (Å) — with intensity of 12,000 μW/cm<sup>2</sup> for 15 to 20 minutes. The Am27C128 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C128, and similar devices, will erase with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2537Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the Am27C128 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

#### Programming the Am27C128

Upon delivery, or after each erasure, the Am27C128 has all 131,072 bits in the "ONE", or HIGH state. "ZEROs" are loaded into the Am27C128 through the procedure of program-

The programming mode is entered when 12.5 ±0.5 V is applied to the Vpp pin,  $\overline{\text{CE}}$  is at V<sub>IL</sub>, and  $\overline{\text{PGM}}$  is at V<sub>IL</sub>.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins

The flowchart in Figure 1 shows AMD's interactive algorithm. Interactive algorithm reduces programming time by using short programming pulses and giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data does not verify, additional pulses are given until it verifies or the maximum is reached. This process is repeated while sequencing through each address of the Am27C128. This part of the algorithm is done at VCC = 6.0 V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. After the interactive programming is completed, an overprogram pulse is given to each memory location; this ensures that all bits have sufficient margin. After the final address is completed, the entire EPROM memory is verified at V<sub>CC</sub> = 5 V ± 5%.

The OTP EPROM Flashrite programming algorithm (shown in Figure 2) reduces programming time by using initial 100 μs pulses followed by a byte verification to determine whether the byte has been successfully programmed. If the data does not verify, an additional pulse is applied for a maximum of 25 pulses. This process is repeated while sequencing through each address of the OTP EPROM.

The Flashrite programming algorithm programs and verifies at V<sub>CC</sub> = 6.25 V and V<sub>PP</sub> = 12.75 V. After the final address is completed, all bytes are compared to the original data with  $V_{CC} = V_{PP} = 5.25 \text{ V}.$ 

#### Program Inhibit

Programming of multiple Am27C128s in parallel with different data is also easily accomplished. Except for  $\overline{\text{CE}}$ , all like inputs of the parallel Am27C128 may be common. A TTL low-level program pulse applied to an Am27C128 PGM input with Vpp = 12.5 ± 0.5 V and CE LOW will program that Am27C128.

A high-level  $\overline{\text{CE}}$  input inhibits the other Am27C128s from being programmed.

#### **Program Verify**

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with  $\overline{\text{OE}}$  and  $\overline{\text{CE}}$  at V<sub>IL</sub>,  $\overline{\text{PGM}}$  at V<sub>IH</sub>, and V<sub>PP</sub> between 12.0 V to 13.0 V.

#### **Auto Select Mode**

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the Am27C128.

To activate this mode, the programming equipment must force 12.0 ± 0.5 V on address line A<sub>9</sub> of the Am27C128. Two identifier bytes may then be sequenced from the device outputs by toggling address line Ao from VIL to VIH. All other address lines must be held at V<sub>IL</sub> during auto select mode.

Byte 0 (A<sub>0</sub> = V<sub>IL</sub>) represents the manufacturer code, and byte 1 (A<sub>0</sub> = V<sub>IH</sub>), the device identifier code. For the Am27C128, these two identifier bytes are given in the Mode Select table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

#### **Read Mode**

The Am27C128 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tacc) is equal to the delay from  $\overline{\text{CE}}$  to output (top). Data is available at the outputs top after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC-tOE.

#### Standby Mode

The Am27C128 has a CMOS standby mode which reduces the maximum VCC current to 100 µA. It is placed in CMOSstandby when  $\overline{\text{CE}}$  is at VCC ± 0.3 V. The Am27C128 also has a TTL-standby mode which reduces the maximum VCC current to 1.0 mA. It is placed in TTL-standby when CE is at VIH. When in standby mode, the outputs are in a high-impedance state, independent of the  $\overline{\text{OE}}$  input.

#### **Output OR-Tieing**

To accomodate multiple memory connections, a two-line control function is provided to allow for:

- 1. Low memory power dissipation, and
- 2. Assurance that output bus contention will not occur.

It is recommended that CE be decoded and used as the primary device-selecting function, while OE be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

#### System Applications

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1-µF ceramic capacitor (high



frequency, low inherent inductance) should be used on each device between V<sub>CC</sub> and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM

arrays, a 4.7-μF bulk electrolytic capacitor should be used between VCC and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

#### MODE SELECT TABLE

	Pins							
Mode		CE	ŌĒ	PGM	A <sub>0</sub>	Ag	Vpp	Outputs
Read		VIL	V <sub>IL</sub>	Х	Х	Х	Vcc	DOUT
Output Disable		V <sub>IL</sub>	ViH	Х	Х	X	Vcc	High Z
Standby (TTL)		VIH	Х	Х	Х	X	V <sub>CC</sub>	High Z
Standby (CMOS)		V <sub>CC</sub> ± 0.3 V	Х	Х	X	Х	V <sub>CC</sub>	High Z
Program		V <sub>IL</sub>	Х	V <sub>IL</sub>	X	Х	Vpp	DIN
Program Verify		V <sub>IL</sub>	V <sub>I</sub> L	VIH	Х	Х	V <sub>PP</sub>	Dout
Program Inhibit		ViH	Х	х	X	Х	Vpp	High Z
Auto Select (Notes 3 & 4)	Manufacturer Code	VIL	VIL	x	V <sub>IL</sub>	V <sub>H</sub>	Vcc	01H
	Device Code	VIL	V <sub>IL</sub>	х	VIH	VH	Vcc	16H

Notes: 1. X can be either  $V_{IL}$  or  $V_{IH}$ 2.  $V_H=12.0~V\pm0.5~V$ 3.  $A_1-A_8=A_{10}-A_{12}=V_{IL}$ 4.  $A_{13}=X$ 5. See DC Programming characteristics for  $V_{PP}$  voltage during programming.

# ABSOLUTE MAXIMUM RATINGS

Storage Temperature:	
OTP Products	65 to +125°C
All Other Products	65 to +150°C
Ambient Temperature	
with Power Applied	55 to +125°C
Voltage with Respect to Ground:	
All pins except Ag, Vpp, and	
V <sub>CC</sub>	0.6 to V <sub>CC</sub> +0.5 V
As and Vpp	0.6 to 13.5 V
V <sub>CC</sub>	0.6 to 7.0 V

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

Notes: 1. Minimum DC voltage on input or I/O is -0.5 V.

During transitions, the inputs may undershoot GND to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O is V<sub>CC</sub> +0.5 V which may overshoot to V<sub>CC</sub> +2.0 V for periods up to 20 ns.

 For Ag and Vpp the minimum DC input is -0.5 V. During transitions, Ag and Vpp may undershoot GND to -2.0 V for periods of up to 20 ns. Ag and Vpp must not exceed 13.5 V for any period of time.

#### **OPERATING RANGES**

Commercial (C) Devices Case Temperature (Tc)
Industrial (I) Devices Case Temperature (Tc)40 to +85°C
Extended Commercial (E) Devices Case Temperature (T <sub>C</sub> )
Military (M) Devices Case Temperature (T <sub>C</sub> )55 to +125°C
Supply Read Voltage: VCC/Vpp for Am27C128-XX5+4.75 to +5.25 VCC/Vpp for Am27C128-XX0+4.50 to +5.50 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 4, 5 & 8)

#### TTL and NMOS inputs

Parameter Symbol	Parameter Description	Test Cond	ditions	Min.	- Max.	Unit
VoH	Output HIGH Voltage	I <sub>OH</sub> = -400 μA		2.4		V
VOL	Output LOW Voltage	I <sub>OL</sub> = 2.1 mA			0,45	
VIH	Input HIGH Voltage		2.0	V <sub>CC</sub> + 0.5	V	
VIL	Input LOW Voltage			-0.3	+0.8	V
714		V 0 V 1- V	C/I Devices		1.0	μΑ
(FI	Input Load Current	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	E/M Devices		5.0	μ
			C/I Devices		10	μ,
lo	Output Leakage Current	V <sub>OUT</sub> ≠ 0 V to V <sub>CC</sub>	E/M Devices	10		, m.
	V <sub>CC</sub> Active	CE = V <sub>IL</sub> , f = 5 MHz,	C/I Devices		30	m/
ICC1	Current (Notes 5 & 9)	I <sub>OUT</sub> = 0 mA (Open Outputs)	E/M Devices		50	
	V <sub>CC</sub> Standby Current	CE = VIH.	C/I Devices		1.0	m/
ICC2	(Note 9)	OE = VIL		1.0		
<sup>1</sup> PP1	Vpp Supply Current (Read)	CE = OE = V <sub>IL</sub> , V <sub>PP</sub> =		100	μA	

# **CMOS** Inputs

Parameter Symbol	Parameter Description			Min.	Max.	Unit	
VoH	Output HIGH Voltage	l <sub>OH</sub> = -400 μA		2.4			
VoL	Output LOW Voltage	I <sub>OL</sub> = 2.1 mA		0.45			
VIH	Input HIGH Voltage			V <sub>CC</sub> -0.3	V <sub>CC</sub> + 0.3	V	
VIL	Input LOW Voltage			-0.3	+ 0.8	٧	
-112	<u> </u>		C/I Devices	1.0		μΑ	
fLI	Input Load Current	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	E/M Devices		5,0	μΛ	



### DC CHARACTERISTICS over operating range unless otherwise specified (Cont'd.)

Parameter Symbol	Parameter Description	Test Cond	ditions	Min.	<b>M</b> ax.	Unit
I	Output Laskana Current	V. 0.V.1- V	C/I Devices			
ILO	Output Leakage Current	V <sub>OUT</sub> = 0 V to V <sub>CC</sub>	E/M Devices		10	μΑ
	V <sub>CC</sub> Active	CE = V <sub>IL</sub> , f = 5 MHz,	C/I Devices		25	4
ICC1	Current (Notes 5 & 9)	I <sub>OUT</sub> = 0 mA (Open Outputs)	E/M Devices		25	mA
laa-	V <sub>CC</sub> Standby Current	CE = V <sub>CC</sub> ± 0.3 V	C/I Devices		100	
ICC2	(Note 9)	QE = ACC.∓ 0.9 A		120	μΑ	
I <sub>PP1</sub>	Vpp Supply Current (Read) (Notes 6 & 9)	CE = OE = V <sub>IL</sub> , V <sub>PP</sub> :		100	μΑ	

#### CAPACITANCE (Notes 2, 3, & 7)

Parameter Symbol	Parameter Description	Test Conditions	Тур.	Max.	Unit
C <sub>IN1</sub>	Address Input Capacitance	V <sub>IN</sub> = 0 V	8	12	pF
C <sub>IN2</sub>	OE Input Capacitance	V <sub>IN</sub> = 0 V	12	20	рF
C <sub>IN3</sub>	CE Input Capacitance	V <sub>IN</sub> = 0 V	9	12	рF
Cour	Output Capacitance	V <sub>OUT</sub> = 0 V	8	12	pF

Notes: 1. VC<sub>C</sub> must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.
2. Typical values are for nominal supply voltages.
3. This parameter is only sampled and not 100% tested.
4. Caution: The Am27C128 must not be removed from, or inserted into, a socket or board when Vpp or V<sub>CC</sub> is applied.
5. I<sub>CC1</sub> is tested with OE = VI<sub>II</sub> to simulate open outputs.
6. Maximum active power usage is the sum of I<sub>CC</sub> and I<sub>PP</sub>.
7. T<sub>A</sub> = 25°C, f = 1 MHz.
8. Minimum DC input voltage is -0.5 V. During transitions, the inputs may undershoot to -2.0 V for periods less than 20 ns. Maximum DC voltage on output pins is V<sub>CC</sub> +0.5 V which may overshoot to V<sub>CC</sub> +2.0 V for periods less than 20 ns.
9. For Am27C128-305, I<sub>CC1</sub> = 50mA, I<sub>CC2</sub> (TTL) = 5mA, I<sub>CC2</sub> (CMOS) = 500µA, and I<sub>PP1</sub> (Read) = 1mA maximum.

# SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3, & 4)

Parameter	Symbols	·			Am27C128								
JEDEC	Standard	Parameter Description	Test Condit	Test Conditions		-70, -75	-90, -95	-120, -125	-150, -155	-200, -205	-250, -255	-300, -305	Unit
tavqv	†ACC	Address to Output Delay	CE = OE = VIL	Min. Max.	55	70	90	120	150	200	250	300	пѕ
tELQV	tCE	Chip Enable to Output Delay	ŌĒ = VIL	Min.	55								ns
tGLQV	t <sub>OE</sub>	Output Enable to	CE = VIL	Max. Min.		70	90	120	150	200	250	300	ns
GLQY		Output Delay Output Enable		Max.	- 35	40	40	50	65	75	100	120	"
tehoz. tghoz	t <sub>DF</sub>	HIGH to Output Float (Note 2)		Max.	25	25	25	35	50	55	60	75	ns
taxox	ф	Output Hold from Addresses, CE, or		Min.	0	0	0	0	0	0	0	0	ns
·AAQA		OE, whichever occurred first		Max					•				115

Notes: 1. V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub>, and removed simultaneously or after V<sub>PP</sub>.

2. This parameter is only sampled and not 100% tested.

3. Caution: The Am27C128 must not be removed from, or inserted into, a socket or board when V<sub>PP</sub> or V<sub>CC</sub> is applied.

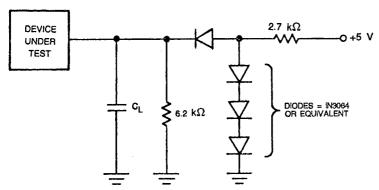
4. For the -55, -70, -75:

Output Load: 1 TTL gate and C<sub>L</sub> = 30 pF,
Input Rise and Fall Times: 20 ns,
Input Pulse Levels: 0 to 3 V,
Timing Measurement Reference Level -1.5 V inputs and outputs.

For all other Versions:

Output Load: 1 TTL gate and C<sub>L</sub> = 100 pF,
Input Rise and Fall Times: 20 ns,
Input Pulse Levels: 0.45 to 2.4 V,
Timing Measurement Reference Level: 0.8 V and 2 V for inputs and outputs.

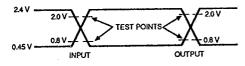
#### SWITCHING TEST CIRCUIT



TC003193

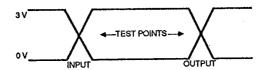
 $C_L$  = 100 pF including jig capacitance (30 pF for -55, -70, and -75)

#### SWITCHING TEST WAVEFORMS



WF026820

AC Testing: Inputs are driven at 2.4 V for a logic "1" and 0.45 V for a logic "0", Input pulse rise and fall times are ≤20 ns.

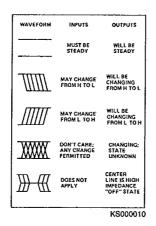


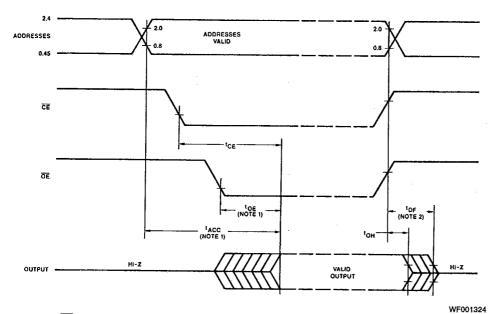
WF026830

AC Testing: Inputs are driven at 3.0 V for a logic "1" and 0 V for a logic "0". Input pulse rise and fall times are  $\leq$  20 ns for -55, -70, and -75 devices.



# SWITCHING WAVEFORMS KEY TO SWITCHING WAVEFORMS





Notes: 1.  $\overline{\text{OE}}$  may be delayed up to  $t_{ACC}$  -  $t_{OE}$  after the falling edge of  $\overline{\text{CE}}$  without impact on  $t_{ACC}$ .

2.  $t_{DF}$  is specified from  $\overline{\text{OE}}$  or  $\overline{\text{CE}}$ , whichever occurs first.

### PROGRAMMING FLOW CHARTS

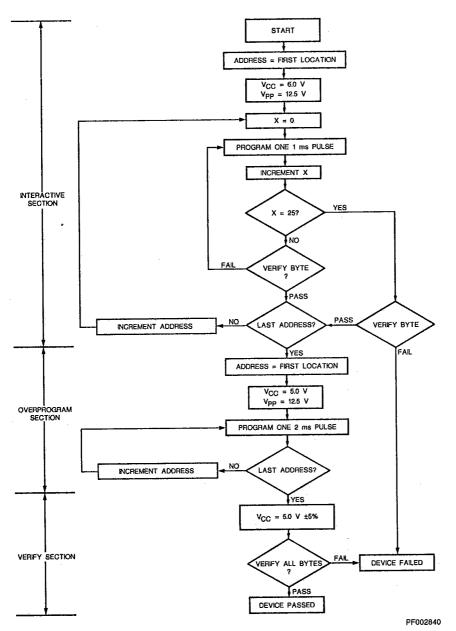


Figure 1. Interactive Programming Flow Chart

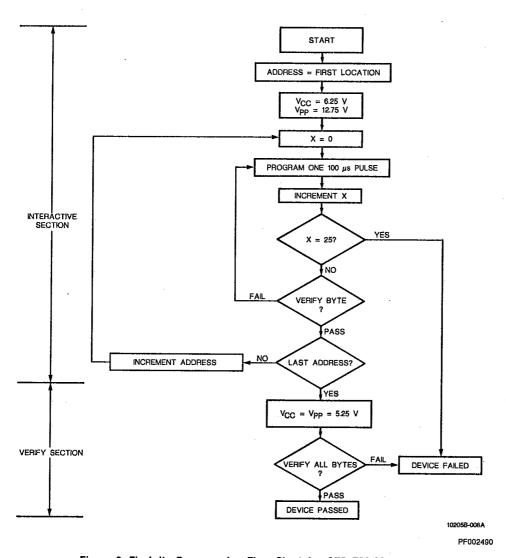


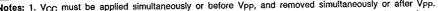
Figure 2. Flashrite Programming Flow Chart for OTP EPROM

# DC PROGRAMMING CHARACTERISTICS (TA = +25°C ±5°C) (Notes 1, 2, & 3).

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max. 10.0	Unit μA
	Input Current (All Inputs)	VIN = VIL or VIH			
V <sub>IL</sub>	Input LOW Level (All Inputs)		-0.3	0.8	V
V <sub>IH</sub>	Input HIGH Level		2.0	V <sub>CC</sub> + 0.5	٧
V <sub>OL</sub>	Output LOW Voltage During Verify	During Verify I <sub>OL</sub> = 2.1 mA		0.45	٧
V <sub>OH</sub>	Output HIGH Voltage During Verify	I <sub>OH</sub> = ~400 μA	2.4		٧
V <sub>H</sub>	Ag Auto Select Voltage		11.5	12.5	V
Іссз	V <sub>CC</sub> Supply Current (Program & Verify)			50	mA
Ipp2	Vpp Supply Current (Program)	CE = VIL, OE = VIH		30	mA
V <sub>CC1</sub>	Interactive Supply Voltage		5.75	6.25	٧
V <sub>PP1</sub>	Interactive Programming Voltage		12.0	13.0	٧
VCC2	Flashrite Supply Voltage		6.00	6.50	V
V <sub>PP2</sub>	Flashrite Programming Voltage		12.5	13.0	V

# SWITCHING PROGRAMMING CHARACTERISTICS ( $T_A = +25$ °C $\pm 5$ °C) (Notes 1, 2, & 3).

Parameter Symbols		Parameter				
JEDEC	Standard	Description		Min.	Max.	Unit
†AVEL	tas	Address Setup Time		2		μs
<sup>†</sup> DZGL	toes	OE Setup Time		2		μs
TELPL	tCES	CE Setup Time		2		μs
tovel	t <sub>DS</sub>	Data Setup Time		2		μs
tGHAX	<sup>t</sup> AH	Address Hold Time		0 .		μs
†EHDX	t <sub>DH</sub>	Data Hold Time		2		μs
tGHQZ	tDFP	Output Enable to Output Float Delay		0	130	ns
typs	tvps	V <sub>PP</sub> Setup Time		2		μs
†ELEH1	t <sub>PW</sub>	PGM Program Pulse Width	Flashrite	95	105	μs
			Interactive	0.95	1.05	μs
tELEH2	topw	PGM Overprogram Pulse Width (Interactive)		1.95	2.05	ms
tvcs	tvcs	V <sub>CC</sub> Setup Time		2		με
tGLQV	toE	Data Valid from OE			150	ns



Notes: 1. V<sub>CC</sub> must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp.

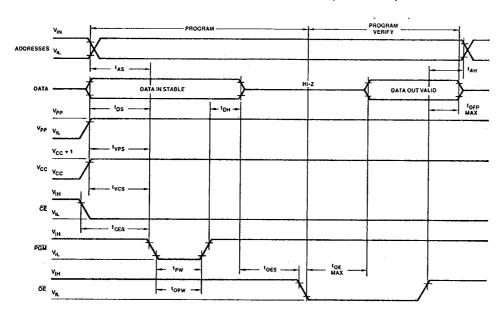
2. When programming the Am27C128, a 0.1-μF capacitor is required across Vpp and ground to suppress spurious



voltage transients which may damage the device.

3. Programming characteristics are sampled but not 100% tested at worst-case conditions.

#### PROGRAMMING ALGORITHM WAVEFORMS (Notes 1 & 2)



WF000555

Notes: 1. The input timing reference level is 0.8 V for  $V_{IL}$  and 2 V for  $V_{IH}$ .

2.  $t_{OE}$  and  $t_{DFP}$  are characteristics of the device, but must be accommodated by the programmer.